Customer Specific Processes (CUSP)

Partner for Wafer Process Outsourcing and Fabless Company Demands
Customer Specific Process Transfers, Development and Volume Manufacturing

Your Advantage is our Special Competence:
- Development and Production of Modular CMOS Technologies with Integration of:
  - Advanced Analog
  - High Voltage
  - Non Volatile
  - Sensors
  - BiCMOS
- Development and Production of Advanced Special Processes:
  - MEMS
  - SOI-CMOS
  - DI-BCDMOS
  - TFT on Quartz Wafers
  - VDMOS
- Technology Transfer:
  - More than 25 transfers of CUSP in last 10 years
  - Transfers of several X-FAB technologies between inhouse locations for second sourcing

... because the world is analog.
Silicon Foundry Services

Customer Specific Processes (CUSP)

You Profit from our Mature Basis for Wafer Production
- Over 70,000 8" equiv. wafer starts per month capacity in fabs in Germany, Malaysia, USA and UK
- 150 and 200 mm wafers
- Clean room class 1-10 & 100 with SMIF environment
- State-of-the-art equipment
- Feature sizes 0.13 - 1.0 μm
- Integrated quality and environmental management system / ISO14001 and ISO TS 16949 certified
- Staff of more than 450 highly-qualified engineers for process development, improvement and quality assurance
- Over 10 years experience in production management and logistics
- Over 10 years experience in managing of Wafer Foundry business including prototyping, Multiproject and Multilayer reticles
- High flexibility and competence in handling of different technologies simultaneously in production
- Competitive production cost structure
- Equipment and competence for additional services like backgrinding, dicing, wafersort

Typical Process Transfer Flow

1. Nondisclosure, Technical, Commercial Agreements
2. Feasibility Assessment
3. Project Planning
4. Process Installation and Verification
5. Qualification and Validation
6. Start of Production